

SOT1252

Plastic earless flanged cavity package; 6 leads

8 February 2016

Package information

1. Package summary

Terminal position code	D (double)
Package type descriptive code	DFM8
Package type industry code	DFM8
Package style descriptive code	DFM (double-ended flange mount)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	24-5-2013

Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	31.04	-	31.24	31.44	mm
E	package width	9.2	-	9.4	9.6	mm
A	seated height	4.18	-	4.415	4.65	mm
e	nominal pitch	-	-	18.03	-	mm
n ₂	actual quantity of termination	-	-	8	-	



2. Package outline

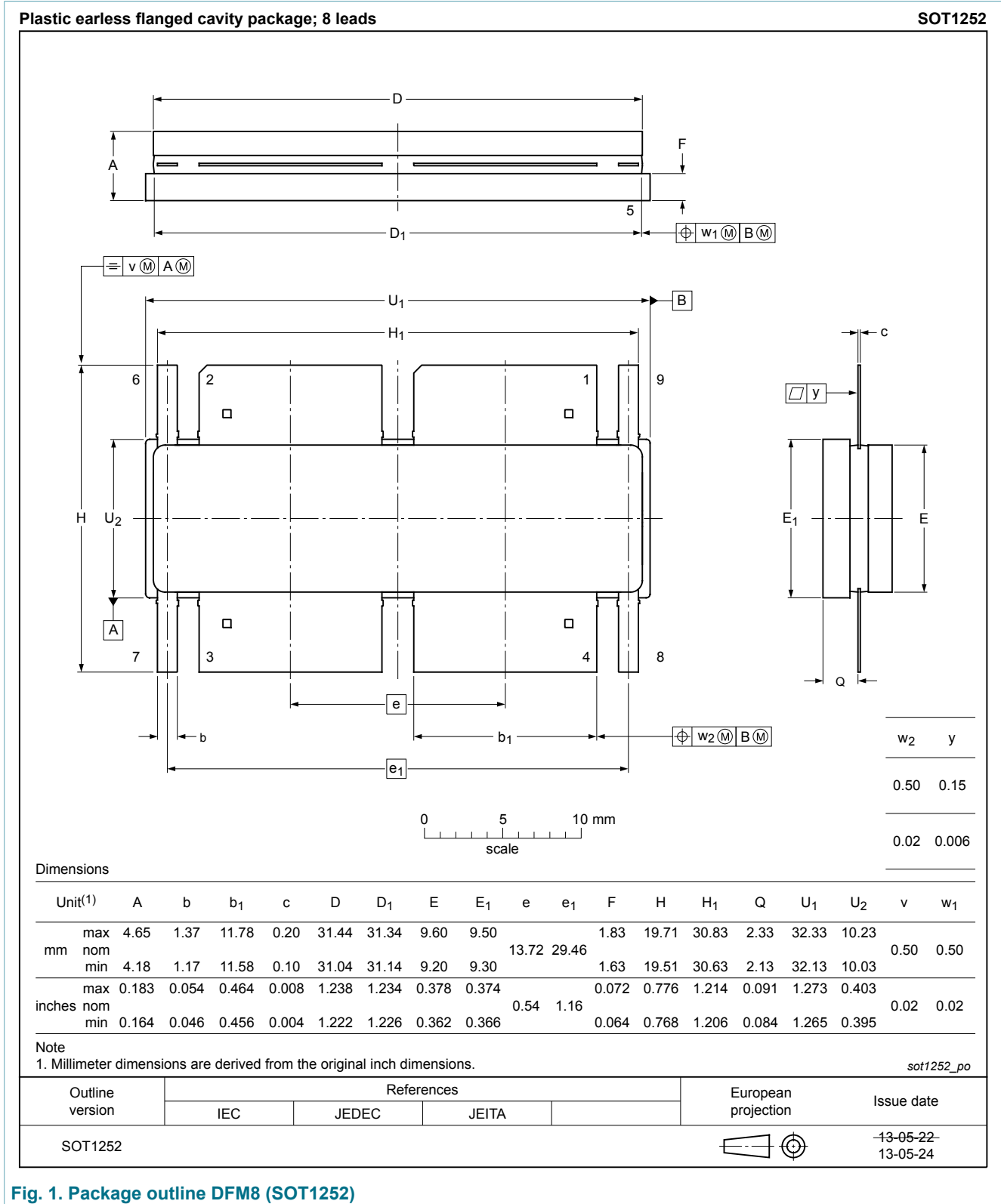


Fig. 1. Package outline DFM8 (SOT1252)

3. Legal information

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4. Contents

1. Package summary.....	1
2. Package outline.....	2
3. Legal information.....	3

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